

International Application No.: PCT/JP2005/012403

U.S. Patent Application No.: Unknown

June 14, 2006

Page 3 of 8

IN THE ABSTRACT:

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following new Abstract of the Disclosure:

International Application No.: PCT/JP2005/012403

U.S. Patent Application No.: Unknown

June 14, 2006

Page 4 of 8

ABSTRACT OF THE DISCLOSURE

A composite ceramic substrate includes a ceramic substrate having surface-mounted components mounted thereon, external terminal electrodes connecting wiring patterns disposed on the ceramic substrate and surface electrodes of a motherboard, and a convex leg portion made of resin and arranged such that an end surface supports the external terminal electrodes, and the external terminal electrodes are connected to the wiring patterns via a via-hole conductor provided in the leg portion.